

CALS/EC Korea '99

Seoul, Korea

July 10-12, 1999



## EC/CALS-related Projects in the Engineering Information Systems Lab

Robert E. Fulton and Russell S. Peak

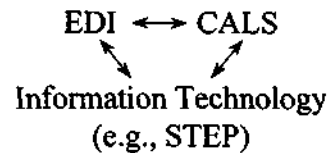
Georgia Institute of Technology  
CALS Technology Center  
Engineering Information Systems Lab  
eislab.gatech.edu

## Georgia Tech CALS Technology Center

Established 1988 by Profs. Robert E. Fulton and James I. Craig

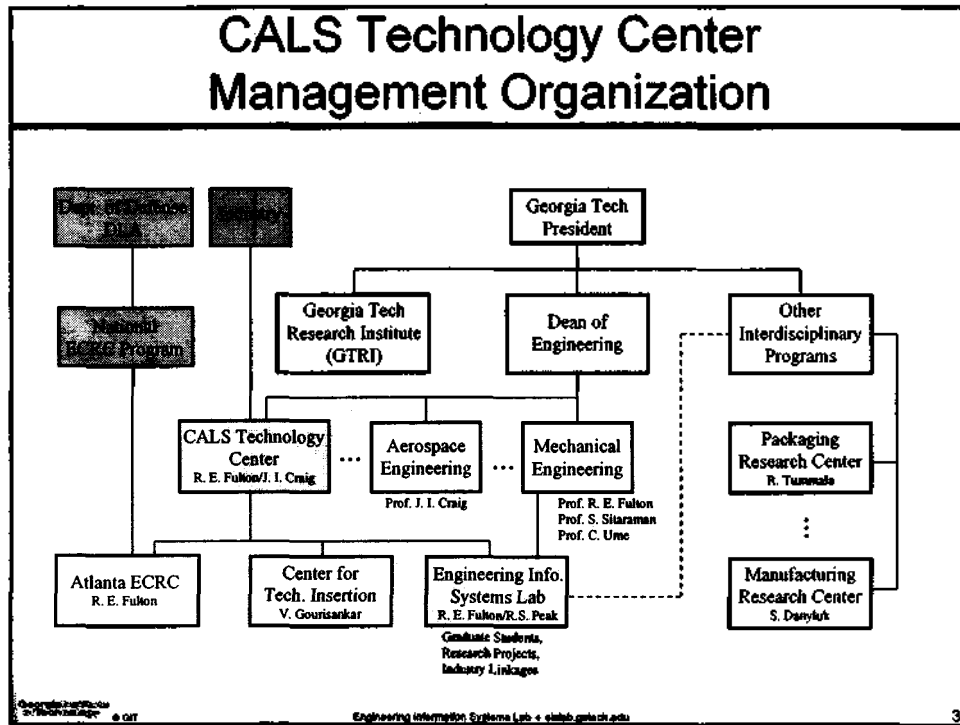
*Information Technology for Life Cycle Engineering and Business Applications*

**THRUSTS** - Applied Research  
Graduate Students  
Demonstration Projects  
Education/Training  
Consulting  
Technology Transfer



### EXAMPLE SPONSORS

Digital Equipment	Motorola	Boeing
US Air Force	DARPA	SDRC
US Army AMCOM	DoD / DLA	NASA
General Motors	NCR	Bell South
Shinko Electric	Lockheed	NSF
Emory Hospital	Russell Mfg.	IBM
GIT Material Handling Research Center Consortium		
GIT Manufacturing Research Center Consortium		



- ### CALs Technology Center Divisions
- ◆ **Engineering Information Systems (EIS) Lab**
    - Applied Research ↔ Industry Projects
    - Graduate Students, University Courses
  - ◆ **Atlanta Electronic Commerce Resource Center (ECRC)**
    - Helping DoD Vendors Move Up the Electronic Commerce Continuum
    - Training, Outreach, Technical Support & Services
  - ◆ **Center for Information Technology Insertion (CITI)**
    - Industrial-Strength Information Technology Solutions
- Engineering Information Technology  
Research, Education, & Insertion*
- Copyright © 1999 by Georgia Tech. Engineering Information Systems Lab • eisl@georgia-tech.edu

<b>EIS Lab People</b>	
<b>Faculty &amp; Staff</b> Tal Cohen - Researcher Robert Fulton - Director, Professor Haruko Peak - Technical Assistant Russell Peak - Asst. Director, Researcher Andrew Scholand - Researcher Adrienne Rollerson - Student Assistant Miyako Wilson - Researcher CALs Technology Center Staff	<b>Graduate Researchers</b> Angela Birkes Ashok Chandrasekhar Selcuk Cimtalay Xiaoling He Chien Hsiung Donald Koo Dennis Ma M.C. Ramesh (Trilogy) Andrew Scholand Srivatsa Shamanna (ITI) Miyako Wilson Sai Zeng
<b>Visiting Researchers</b> Sunn-ho Kim, Myong-Ji University, Korea Changhee Han, KAIST, Korea Ryuichi Matsuki, Shinko Electric, Japan	<b>Undergraduate Researchers</b> Steven Smith

Georgia Tech EIS Lab © 2000/02/2001 e.gat Engineering Information Systems Lab • eislab@gatech.edu

<b>EIS Lab Alumni</b>	
<b>Engineering Information Technology CAD/CAE/CAM, Analysis Integration</b>	<b>Parallel Processing</b>
<b>Masters</b> Wei Chang, General Motors Janice Chinn, U. S. Air Force Michael Y. Gabertan, Motorola Neil Hall, IT Co. Trey Jernigen, Lockheed Miyako Wilson, Georgia Tech (3Q99)	<b>PhD</b> C. Chiang, University in Taiwan Kuoning Chiang, Taiwan Super Computer Center Dietmar Goelich, MBB/Daimler Benz Jason Har, Korea Rong Fu Ou, Engineering Consulting Firm Phillip Su, NASA Langley Super Computer Project Sang Synn, Hyundai Heavy Industries Co. Ltd.
<b>PhD</b> Bipin Chadha, Lockheed Gintas Jazbutis, SDRC - Boeing Consultant Deeptendu Majumder, Computervision Corp Russell Peak, Georgia Tech CALs Tech. Center Ravi Rangan, SDRC - Boeing Consultant Diego Tamburini - SDRC - Boeing Consultant Ching-Yang Wang, Boeing Pete Whelan, Sematech Chao-pin Yeh, Motorola Wen Zhou, Motorola	

Georgia Tech EIS Lab © 2000/02/2001 e.gat Engineering Information Systems Lab • eislab@gatech.edu

## Example Information Modeling Research and Industry Linkages

Topic	Graduate Student	Industry Linkage
Engineering Data Modeling Methods	Gintas Jazbutis	AT&T
Database Approach for Design Changes	Tal Cohen	GM
Database Approach for Aircraft Conceptual Design	Neil Hall	Lockheed, McDonnell Douglas
Reengineering Aircraft Maintenance/Repair	Angela Birkes, Tal Cohen	WR-ALC
Laser Scanning of 3D Part Geometry	M. C. Ramesh	WR-ALC
STEP Models for Forging	M. C. Ramesh	Lockheed Martin
Prototype Multimedia Autobroker	Angela Birkes, Chien Hsiung	BellSouth, DEC, Emory Hospital
Virtual Manufacturing Assembly	Chien Hsiung	
Multimedia Database on Olympic Construction	Angela Birkes	
Parametric FEA Modeling Methodology	Wen Zhou	Motorola
Assembly of Product Data to Support Analysis	Diego Tamburini	STEP Tools Inc.
PWA Component Layout Optimization	Andrew Scholand	GT MARC
Electronic Component Design Optimization	Selcuk Cimtalay	GT MARC

## Research Thrusts

- ◆ **Analysis Integration**
  - Design-Analysis Integration (DAI)
  - X-Analysis Integration (XAI)
  - Modular parametric finite element modeling
  - Optimization
- ◆ **Engineering Information Technology**
  - Internet-based engineering service bureaus (ESBs)
  - Engineering change management
  - Product modeling
  - Engineering information standards (e.g., STEP)
- ◆ **Parallel Processing**

### *Applications*

Aerospace, Automotive, Electronic Packaging, etc.

## X-Analysis Integration (XAI/DAI) Research

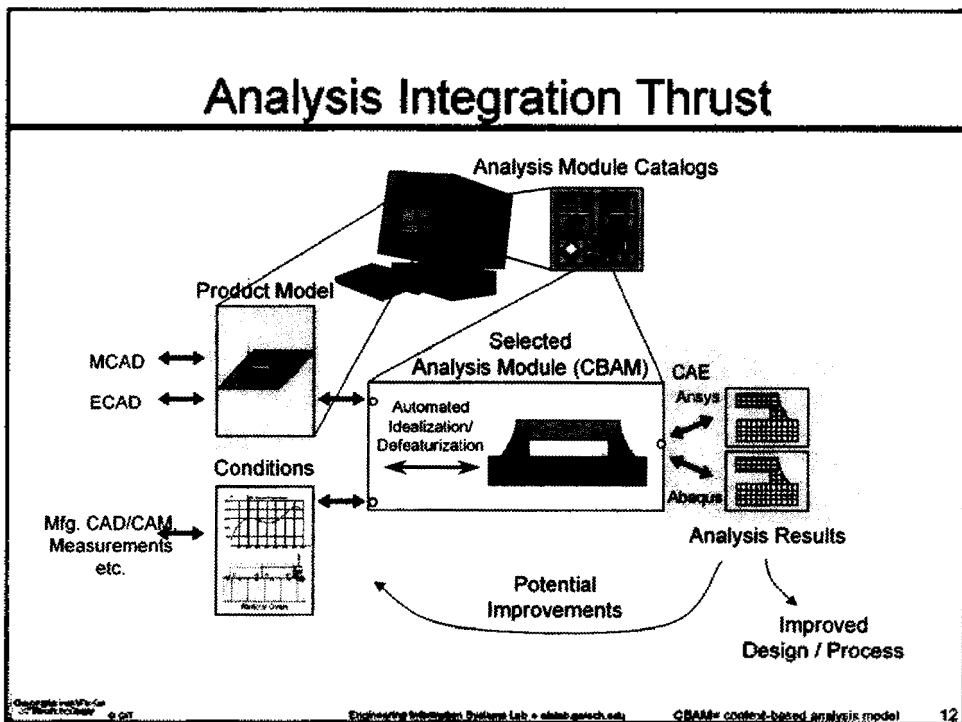
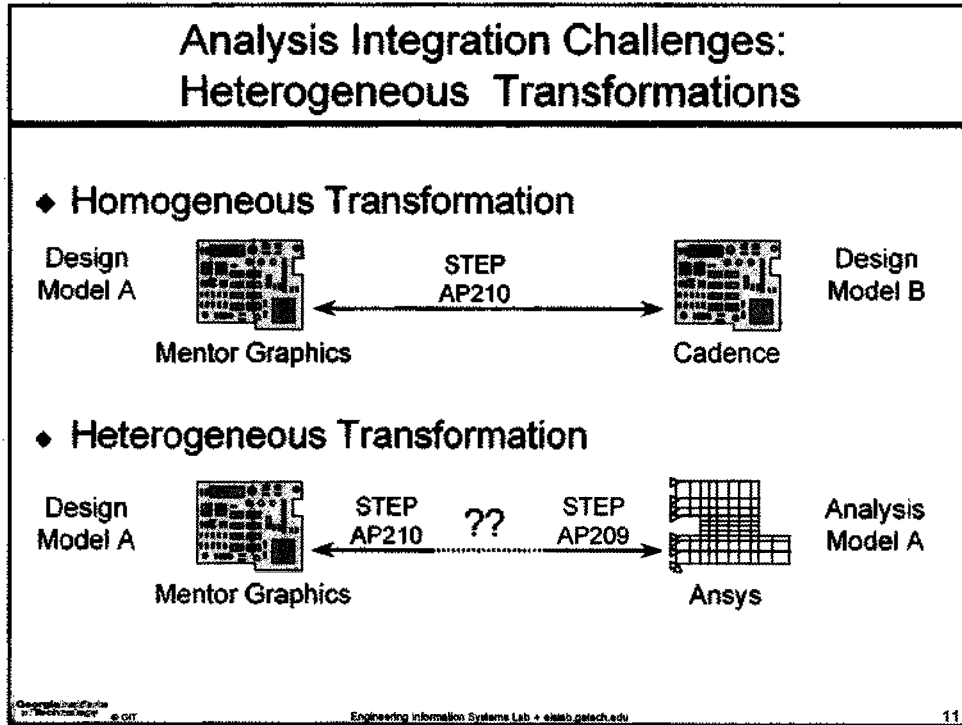
---

Georgia Institute of Technology  
Engineering Information Systems Lab  
eislab.gatech.edu

## Design-Analysis Integration

---

- ◆ **Goal:**
  - Improve the product development process by integrating design and analysis models
- ◆ **Challenges:**
  - Heterogeneous Transformations
  - Diversity: Disciplines, Fidelity, Design Tools, Analysis Tools
- ◆ **One Solution:**
  - The Multi-Representation Architecture (MRA)
- ◆ **Initial Focus:**
  - Automation of routine analysis



## Components of EIS Lab Analysis Integration Technique

- ◆ Conceptual architecture: MRA
- ◆ Methodology
- ◆ General purpose MRA toolkit: *XaiTools*
  - Toolkit architecture
  - Users guide
  - Tutorials (work-in-process)
- ◆ Product/company-specific applications
  - PWA/Bs (ProAM)
  - Aerospace structural analysis (Boeing PSI)
  - Chip packaging/mounting (Shinko)

See <http://eislab.gatech.edu/> for references

Engineering Information Systems Lab • eislab@gatech.edu 13

## Multi-Representation Architecture (MRA) for Design-Analysis Integration

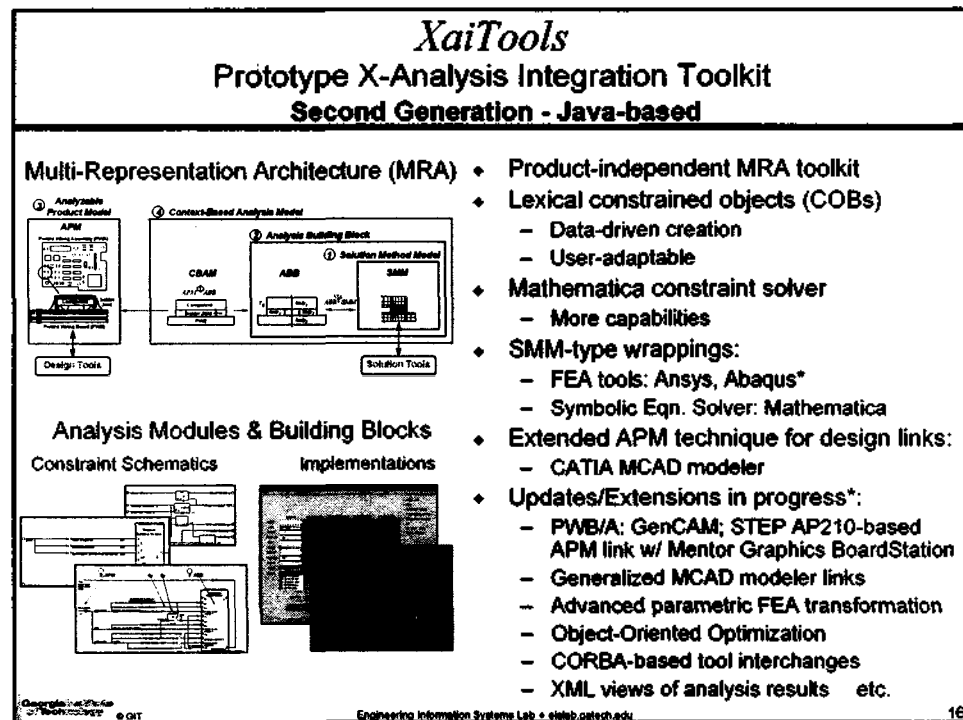
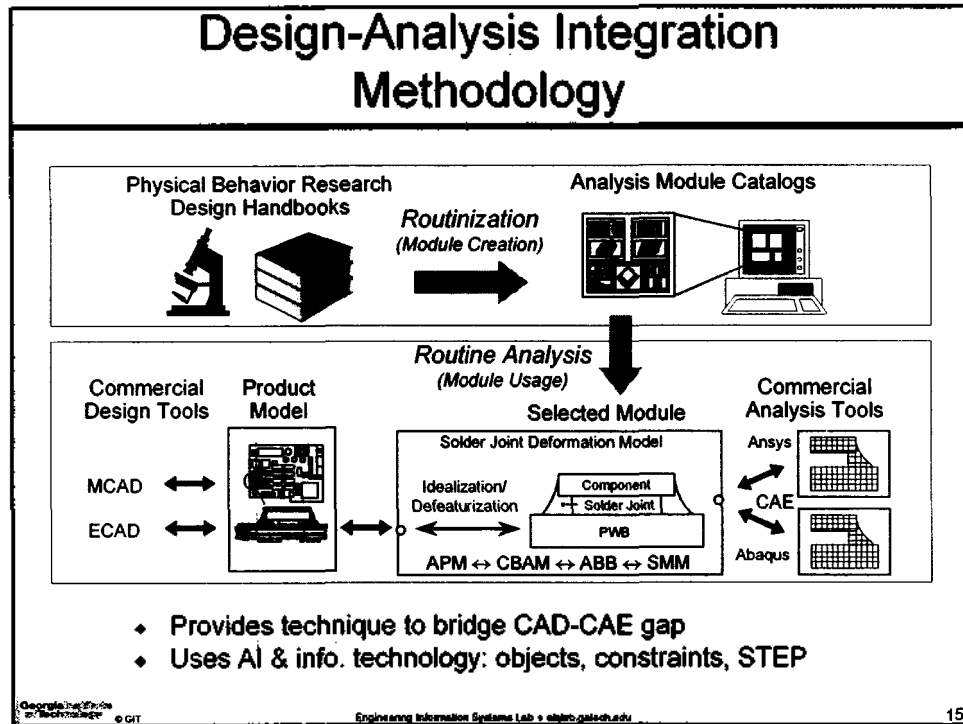
The diagram illustrates the Multi-Representation Architecture (MRA) for Design-Analysis Integration, composed of four main representations (information models):

- ① **Solution Method Model (SMM)**: Contains the **Analysis Building Block (ABB)** and the **Solution Method Model (SMM)**. It is supported by **Solution Tools**.
- ② **Context-Based Analysis Model (CBAM)**: Contains the **Analysis Building Block (ABB)** and the **Context-Based Analysis Model (CBAM)**. It is supported by **Design Tools**.
- ③ **Analyzable Product Model (APM)**: Contains the **Printed Wiring Assembly (PWA)** and the **Printed Wiring Board (PWB)**. It is supported by **Design Tools**.
- ④ **Context-Based Analysis Model (CBAM)**: Contains the **Analysis Building Block (ABB)** and the **Context-Based Analysis Model (CBAM)**. It is supported by **Design Tools**.

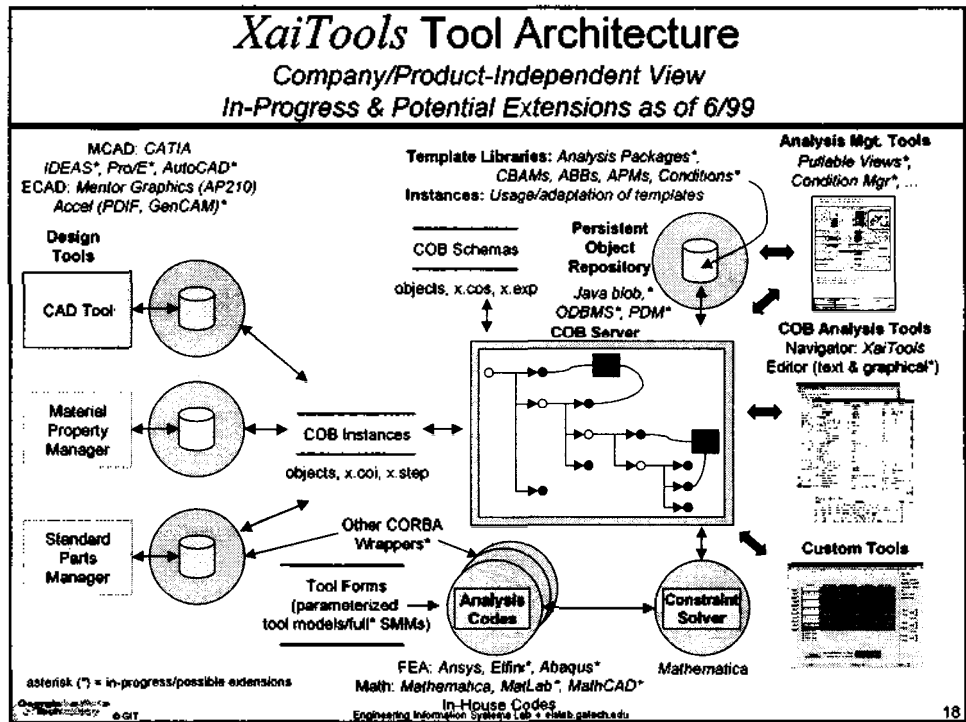
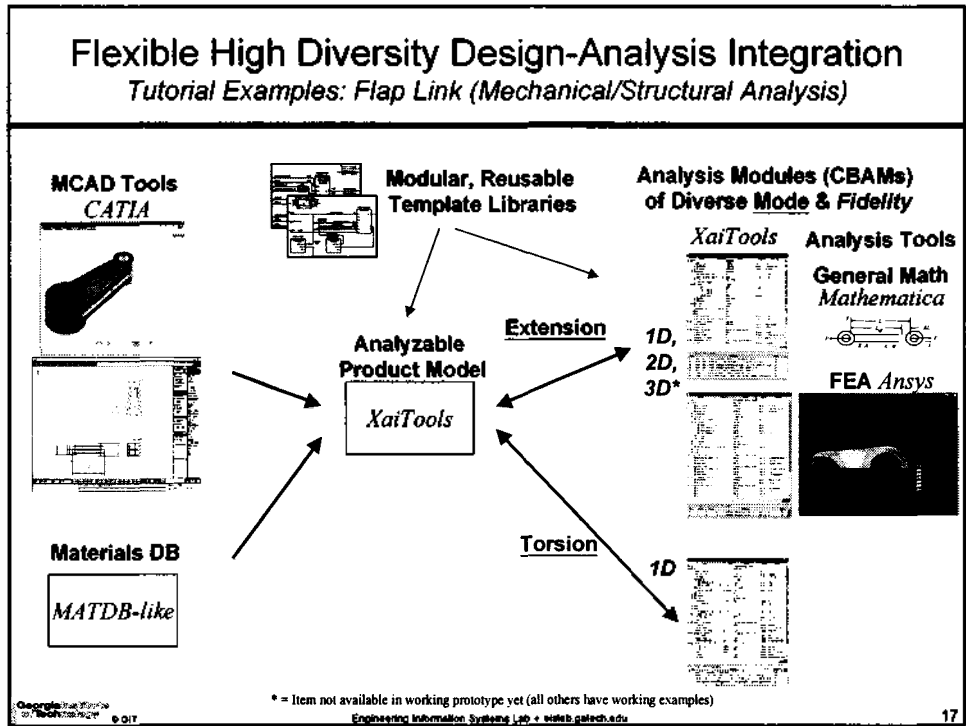
Arrows indicate the flow of information between these models, showing how design information is integrated with analysis models.

- ◆ Composed of four representations (information models)
- ◆ Provides flexible, modular mapping between design & analysis models
- ◆ Creates automated, product-specific analysis modules (CBAMs)
- ◆ Represents design-analysis associativity explicitly

Engineering Information Systems Lab • eislab@gatech.edu 14





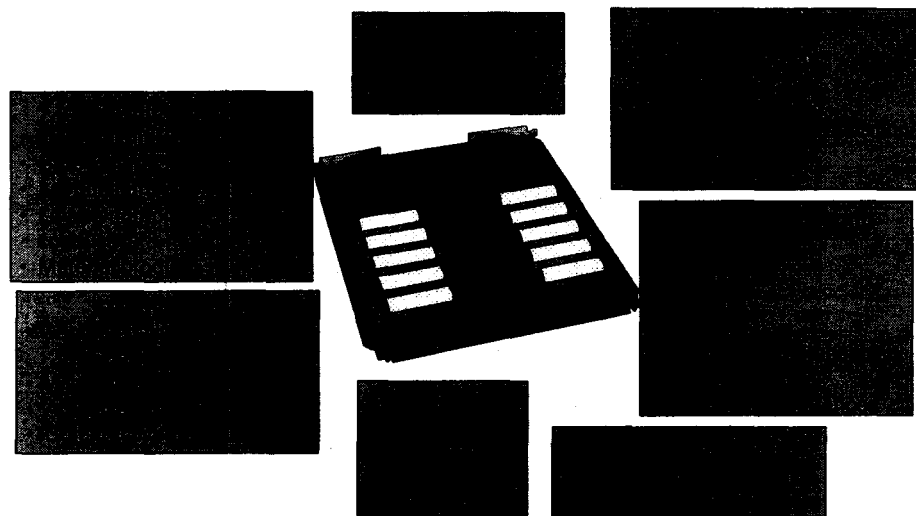


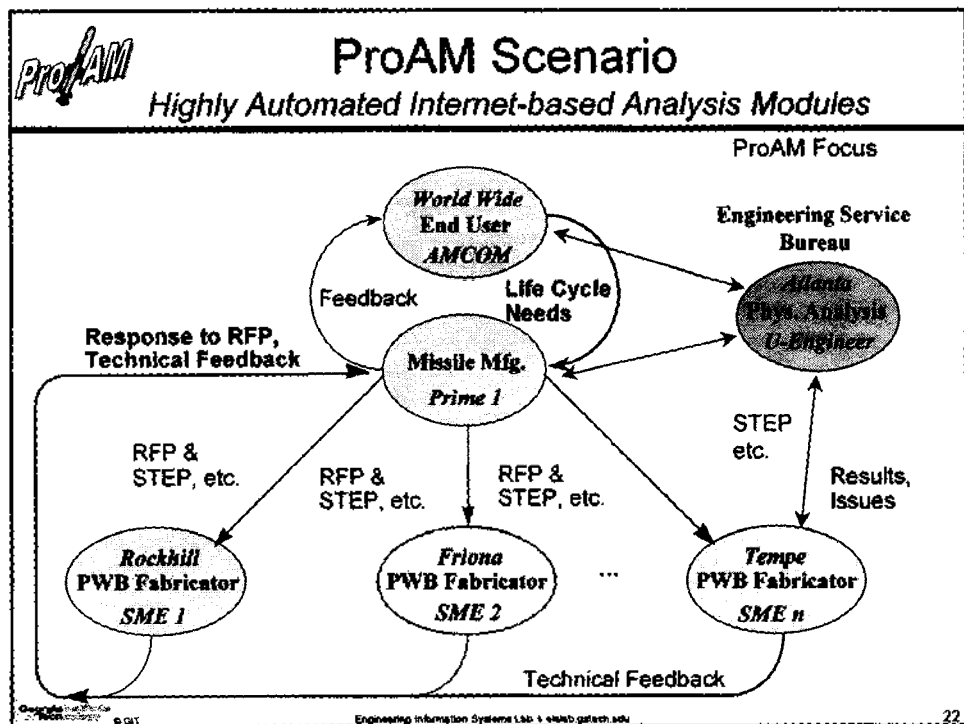
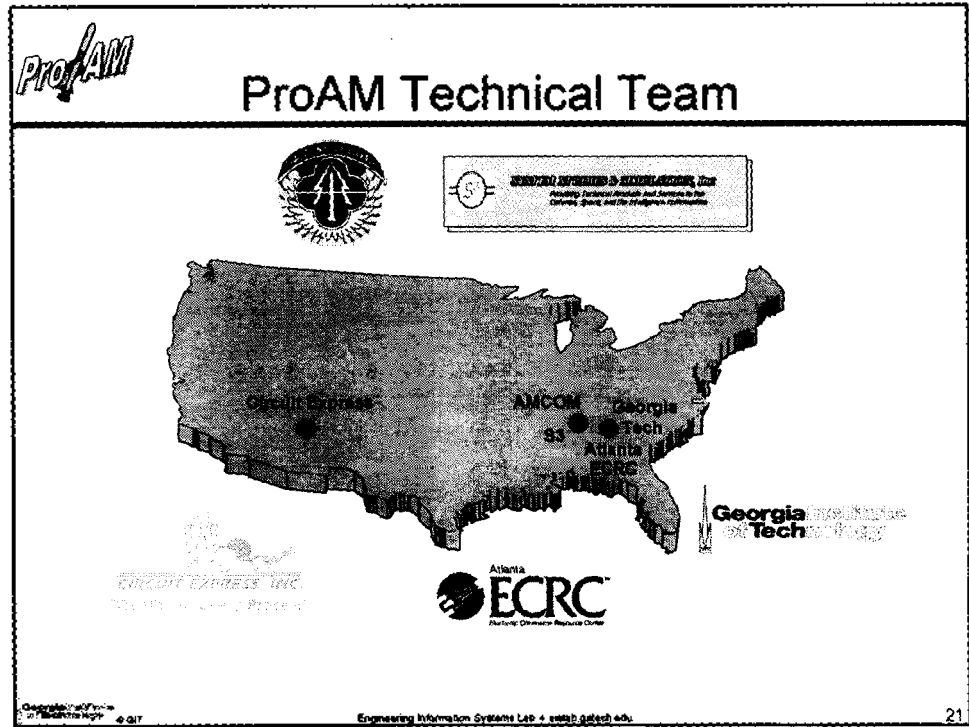
## Example Projects

- ◆ **Team Integrated Electronic Response (TIGER)**
  - Sponsor: Defense Advanced Research Prog. Admin. (DARPA) (SCRA subcontract)
  - Period: 9/95-3/97
- ◆ **Subsystem Interface Integration (SII)**
  - Sponsor: NASA (Lockheed Martin subcontract)
  - Period: 12/97-5/98
- ◆ **Product Data-Driven Analysis in the Life Cycle Support Process**
  - Sponsor: Wright Patterson Air Force Base (WPAFB)
  - Period: 12/97-6/98
- ◆ **Product Data-Driven Analysis in a Missile Supply Chain (ProAM)**
  - Sponsor: Defense Logistics Agency National ECRC Program
  - Stakeholder: U. S. Army Missile Command (AMCOM)
  - Period: 8/97-6/99
- ◆ **Design Analysis Associativity Technology for PSI (PSI-DANTE)**
  - Sponsor: Boeing
  - Period: 9/97-12/98 (Phase 1)
- ◆ **Design Analysis Integration Research for Electronic Packaging**
  - Sponsor: Shinko Electric
  - Period: 1/99-12/99 (Phase 1)



## STEP AP 210 PWA/B Design Information






**Pro/AM** Why Do SME Manufacturers Need Analysis?

- ◆ Typically niche-experts
  - Precise mfg. process knowledge
  - Specialized product design knowledge (ex. PWB laminates)
- ◆ SME analysis needs
  - Product improvements (DFM)
  - Mfg. process troubleshooting
  - Mfg. process optimization
- ◆ More accurate data → Better analysis
- ◆ Bottom line drivers:

*Higher Yields, Lower Cost,  
Better Quality, Fewer Delays*



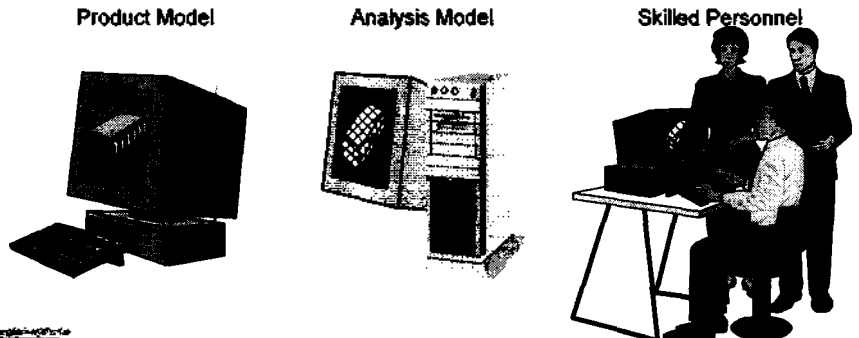
Georgia Institute of Technology © 2007 Engineering Information Systems Lab • eislab@gatech.edu

23

**Pro/AM** Barriers to SME Analysis


- ◆ Lack of awareness
- ◆ High costs of traditional analysis capability
  - Secondary: Specialized Software, Training, Hardware
  - Primary: Model Access/Development, Validation, Usage
- ◆ Lack of domain-specific integrated tools

Product Model      Analysis Model      Skilled Personnel

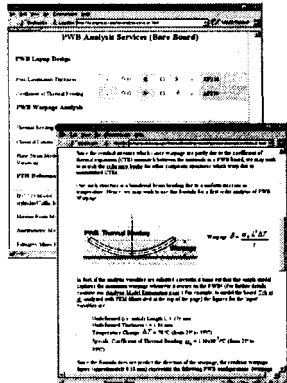
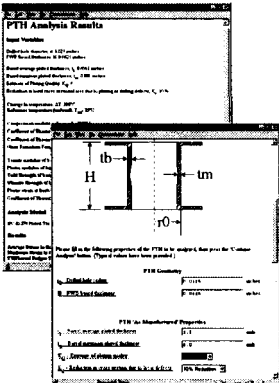
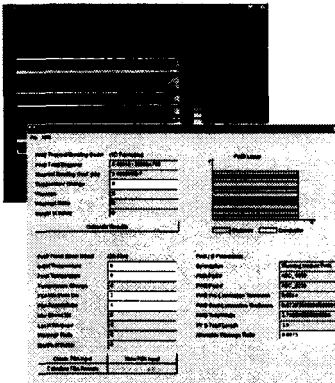


Georgia Institute of Technology © 2007 Engineering Information Systems Lab • eislab@gatech.edu

24




## Internet-based Engineering Service Bureau (ESB) Tools

Analysis Documentation      Ready-to-Use Analysis Modules

*Lower cost, better quality, fewer delays in supply chain*

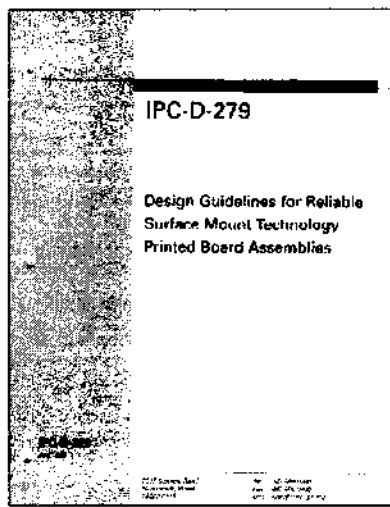
Georgia Tech EIS Lab
Engineering Information Systems Lab • eislab.gatech.edu
25



## Paper-based IPC-D-279 Plated Through Hole Fatigue Analysis

*Tedious to Use*

PTH/PTV Fatigue Life Estimation




$$\sigma_{avg} = \frac{(\alpha_f - \alpha_{cl}) \Delta T + S_f \frac{E_{cl} - E_{cl}'}{E_{cl} E_{cl}'}}{A_f E_f + A_{cl} E_{cl}'}$$

$$\Delta \epsilon_{avg} = \frac{(\alpha_f - \alpha_{cl}) \Delta T \cdot A_f \cdot E_f \cdot E_{cl}' - S_f \cdot A_{cl} \cdot \frac{E_{cl} - E_{cl}'}{E_{cl}}}{A_f \cdot E_f + A_{cl} \cdot E_{cl}'}$$

$$N_f^{-0.6} D_f^{0.75} + 0.9 \frac{S_y}{E} \left[ \frac{e^{D_f}}{0.36} \right]^{0.1785 \log \frac{10^7}{N_f}} - \Delta \epsilon = 0$$

$$N_f(x\%) = N_f(50\%) \left[ \frac{\ln(1 - 0.01x)}{\ln(0.5)} \right]^{\frac{1}{\beta}}$$

Georgia Tech EIS Lab
Engineering Information Systems Lab • eislab.gatech.edu
26



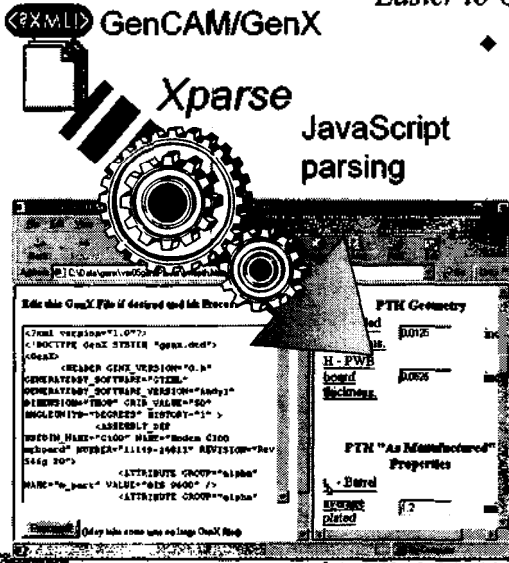
## Product Data-Driven IPC-D-279 PTH Analysis Module

*Easier to Use*

GenCAM/GenX


Xparse

JavaScript parsing



- ◆ Data Driven aspect: Web Browser Processes Neutral File
- + Local Browser Computation
- + Less Errors than manual idealization & re-entry
- + Exhaustive search
- + Data Compression (e.g. 100x)
- + Security

Copyright © 2007
Engineering Information Systems Lab • eisl@eas.gatech.edu
27




## ESB Analysis Module Catalogs & Documentation

PWB Analysis Services (Bare Board)

PWB Layout Design	
Post-Lamination Thickness	f(c) <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input checked="" type="checkbox"/>
Coefficient of Thermal Expanding	f(c) <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input checked="" type="checkbox"/>
PWB Warpage Analysis	
Thermal Bonding Model	f(c) <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input checked="" type="checkbox"/> AP210
Classical Lamina Theory Model	f(c) <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input checked="" type="checkbox"/>
Plate Strain Model (Minors Variation)	f(c) <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input checked="" type="checkbox"/> AP210
PTH Deformation & Fatigue Analysis	
IPC 279 Model (Cylinder/Collar-Minors)	f(c) <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input checked="" type="checkbox"/>
Minors Strain Model	f(c) <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input checked="" type="checkbox"/>
Asymmetric Model	f(c) <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input checked="" type="checkbox"/>
Palmer-Miner Model	f(c) <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input checked="" type="checkbox"/>

Since the residual stresses which cause warpage are partly due to the coefficient of thermal expansion (CTE) mismatch between the materials in a PWB board, we may wish to search the references below for other composite structures which warp due to mismatched CTEs.

One such structure is a laminated beam bending due to a mismatch between its components. Hence, we may wish to use the formula for a first order analysis of PWB Warpage:



$$\text{Warpage } \delta = \frac{\alpha_2 \Delta T}{t}$$

In fact, if the analysis variables are selected correctly, it turns out that this simple model captures the maximum warpage wherever it occurs on the PWB! (For further details, visit our [Analysis Model Enhancement page](#).) For example, to model the board 'Yeh et al.' analyzed with FEM (illustrated at the top of the page) the figures for the 'input' variables are:

Unstressed ( $t = \text{initial}$ ) Length  $L = 276 \text{ mm}$   
 Unstressed Thickness  $t = 1.28 \text{ mm}$   
 Temperature Change  $\Delta T = 76 \text{ }^\circ\text{C}$  (from  $27^\circ\text{C}$  to  $103^\circ\text{C}$ )  
 Specific Coefficient of Thermal Expanding  $\alpha_2 = 1.16 \times 10^{-6} / ^\circ\text{C}$  (from  $27^\circ\text{C}$  to  $103^\circ\text{C}$ )

Since the formula does not predict the direction of the warpage, the residual warpage figure (approximately 0.58 mm) represents the following PWB configurations (warpage):

Copyright © 2007
Engineering Information Systems Lab • eisl@eas.gatech.edu
28

**ProAM**

## Analysis Modules Attributes

**Solution Method** - An indication of model computational cost.

- Formula Based
- Finite Element

**Utility Ranking** - A measure of analysis model validity.

- Demonstration
- Trends
- Magnitude Relative
- Absolute

A "P" indicates that the ranking is backed by physical measurements.

**Test Availability** - A measure of implementation maturity.

- Concept
- Prototype
- Pilot
- Production

**PWB Analysis Services (Bare Board)**

**PWB Layout Design**

Post-Lamination Thickness	$f(x)$	<input checked="" type="radio"/>	<input type="radio"/>	<input type="radio"/>	<input checked="" type="checkbox"/>	AP210
Coefficient of Thermal Expanding	$f(x)$	<input checked="" type="radio"/>	<input type="radio"/>	<input type="radio"/>	<input checked="" type="checkbox"/>	AP210

**PWB Warpage Analysis**

Thermal Bending Model	1D	$f(x)$	<input type="radio"/>	<input type="radio"/>	<input checked="" type="checkbox"/>	AP210
Classical Lamina Theory Model	2D	$f(x)$	<input checked="" type="radio"/>	<input type="radio"/>	<input type="checkbox"/>	✓
Plane Strain Model (Material Variation)	2D		<input type="radio"/>	<input type="radio"/>	<input checked="" type="checkbox"/>	AP210

**PTH Deformation & Fatigue Analysis**

IPC 279 Model (cylinder/Coffin-Manson)	1D	$f(x)$	<input checked="" type="radio"/>	<input checked="" type="radio"/>	<input type="radio"/>	GenX
Manson Beam Model	1D	$f(x)$	<input checked="" type="radio"/>	<input checked="" type="radio"/>	<input type="radio"/>	GenX
Asymmetric Model	2D		<input checked="" type="radio"/>	<input type="radio"/>	<input type="checkbox"/>	GenX
Falrgren-Matrn Model		$f(x)$	<input type="radio"/>	<input type="radio"/>	<input type="checkbox"/>	

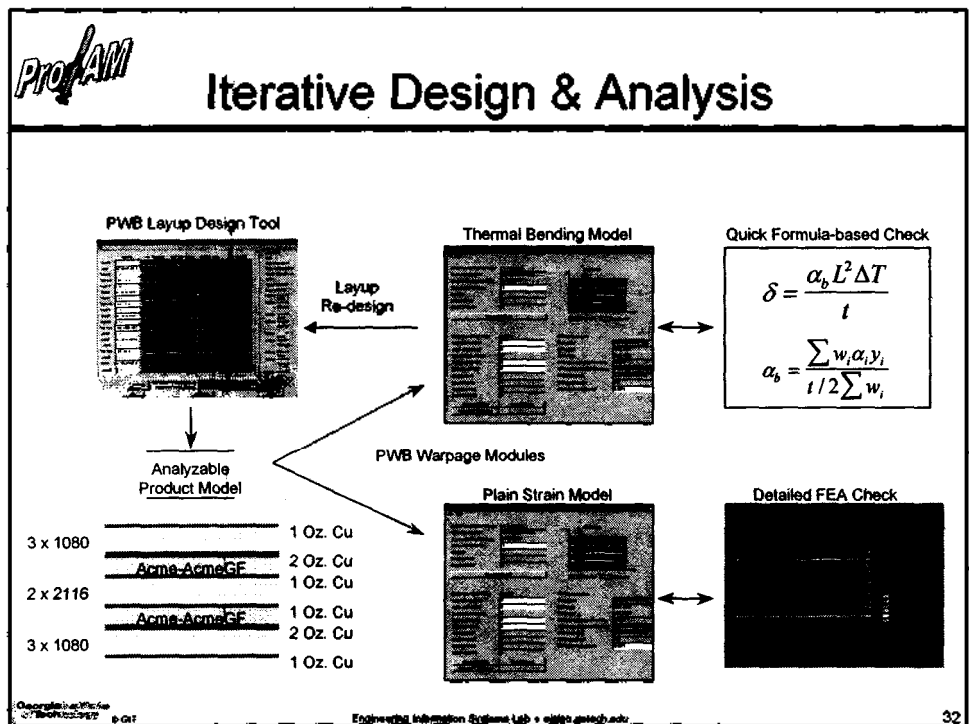
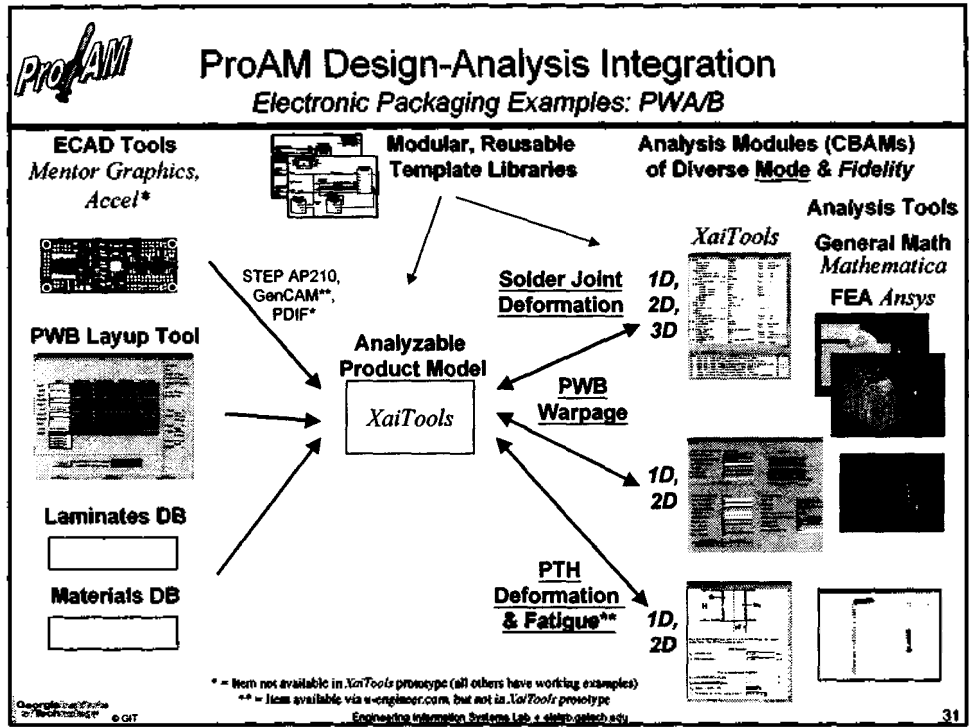
© GIT      Engineering Information Systems Lab • eislab.gatech.edu      29

**ProAM**

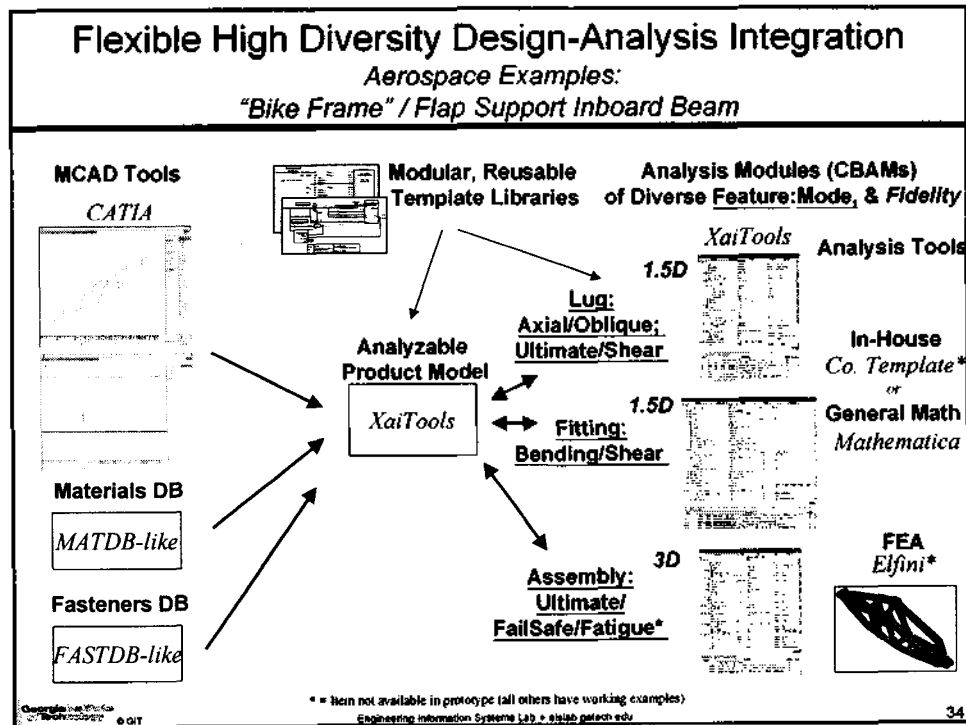
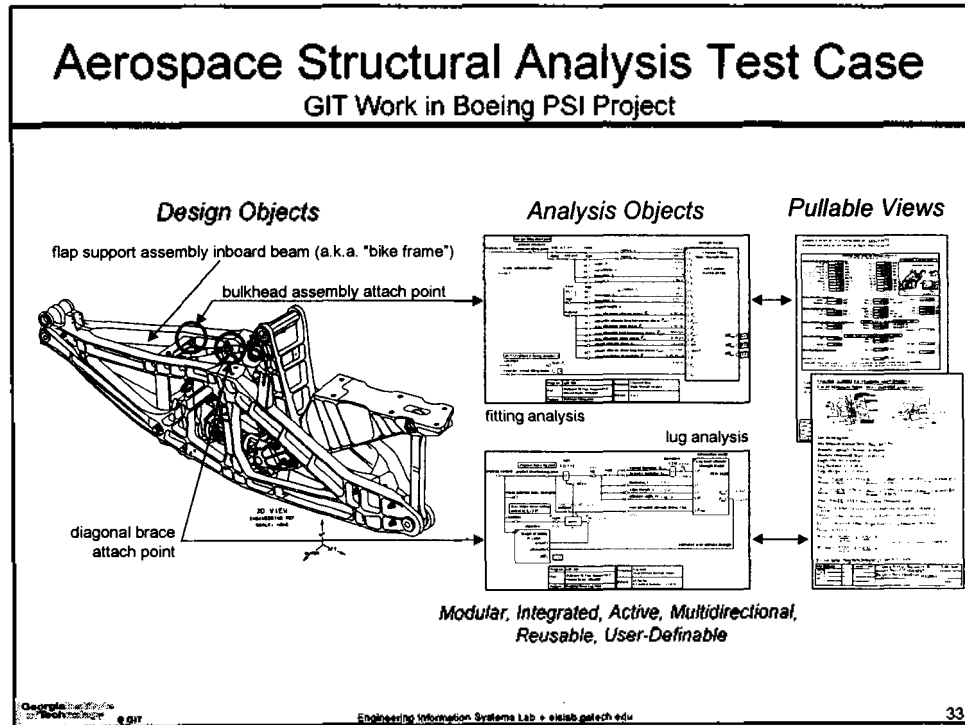
## ESB Characteristics

- ◆ **Self-serve analysis**
  - Pre-developed analysis modules presented in product & process contexts
  - Available via the Internet
  - Optionally standards-driven (STEP, GenCAM ...):
    - » Reduce manual data transformation & re-entry
    - » Highly automated plug-and-play usage
  - Enabled by X-analysis integration technology
- ◆ **Full-serve analysis as needed**
- ◆ **Possible business models:** (beyond ProAM scope)
  - Pay-per-use and/or Pay-per-period
  - Costs averaged across customer base

© GIT      Engineering Information Systems Lab • eislab.gatech.edu      30







## Analysis Integration Summary

- ◆ Strong emphasis on X-analysis integration (XAI/DAI)
- ◆ Multi-Representation Architecture (MRA)
  - Addressing fundamental XAI/DAI issues
  - General methodology --> Flexibility & broad application
- ◆ Relevant project experience and research advances
  - Product data-driven analysis (STEP AP210, GenCAM, etc.)
  - Engineering service bureau (ESB) techniques
  - Object techniques for next generation aerospace analysis systems
- ◆ Research, applications, and technology transfer
  - Analysis integration toolkit: *XaiTools*
  - Pilot commercial ESB: [u-engineer.com](http://u-engineer.com)
  - Company-tailored engineering information systems solutions
- ◆ Industry & government collaboration

## For Further Information ...

- ◆ EIS Lab web site: <http://eislab.gatech.edu/>
  - Publications, project overviews, tools, etc.
  - See Publications, DAI/XAI, Suggested Starting Points
- ◆ Pilot commercial ESB: <http://u-engineer.com/>
  - Internet-based self-serve analysis
  - Analysis module catalog for electronic packaging
  - Highly automated front-ends to general FEA & math tools